

High Efficiency, Synchronous 2-Switch Bidirectional Boost Charge & Buck Discharge Controller

1 Descriptions

SC8804 is a synchronous boost charger controller. It is able to effectively manage charging when input voltage is lower than battery voltage. In charging mode, SC8804 supports trickle charging, constant current (CC) charging and constant voltage (CV) charging management functions automatically.

SC8804 supports very wide input and output voltage range. It is suitable for applications of 1 to 6 series battery. The driver voltage is set to 10V to fully utilize external MOSFETs for maximum efficiency.

SC8804 also supports reverse buck discharging by controlling DIR pin. Under reverse buck mode, SC8804 outputs a lower VBUS voltage from VBAT. It also supports input current limit, output current limit, dynamic output voltage regulation, internal current limit, and over temperature protections to ensure safety under different abnormal conditions.

SC8804 adopts 32 pin QFN 4x4 package.

3 Applications

- Power Bank
- USB HUB
- Smart USB Sockets
- USB PD

2 Features

- Boost charging mode supports charging functions for 1 to 6 battery in series, including trickle charging, CC charging, CV charging and charging termination function
- Reverse buck mode operation (discharging mode)
- Wide input voltage range (VBUS in charging mode): 2.7V to 36 V
- Wide reverse output range (VBAT in discharging mode) : VBAT to 36 V
- Dynamic adjustable discharging voltage by PWM signal
- High efficient buck/boost operation
- Integrated 10V, 2A gate driver
- Adjustable frequency from 200KHz to 600KHz
- Internal current limit
- Under voltage protection
- QFN-32 package

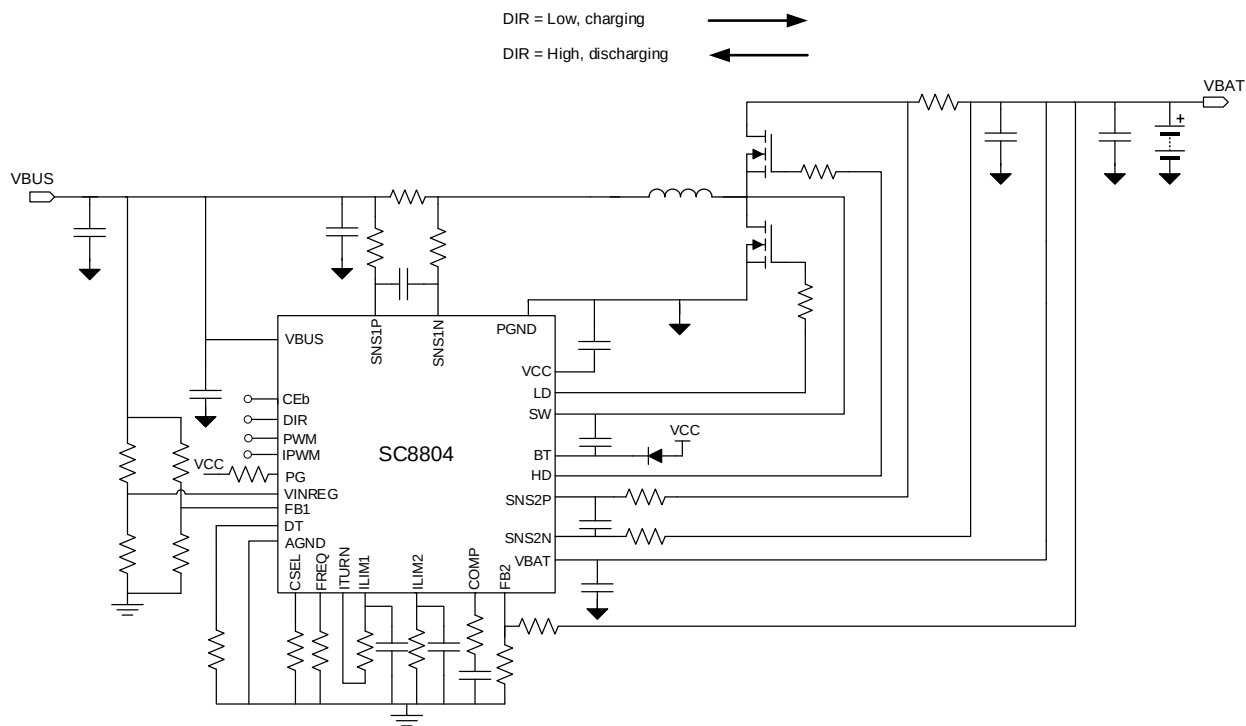
4 Device Information

ORDER NUMBER	PACKAGE	BODY SIZE
SC8804QDER	32 pin QFN	4mm x 4mm x 0.75mm

5 Device Selection Table

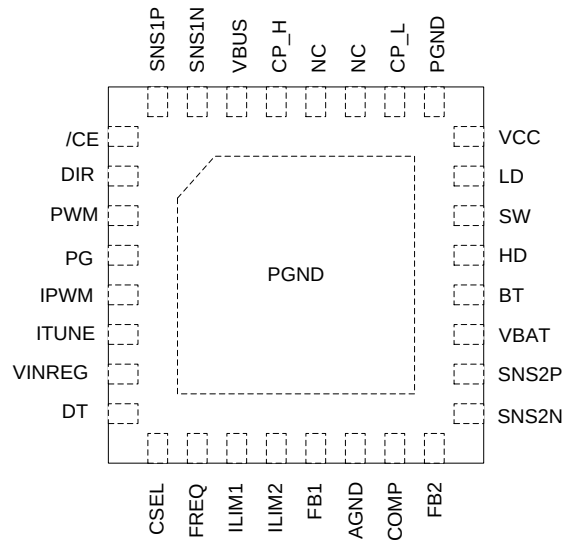
ORDER NUMBER	SC8801	SC8802	SC8803	SC8804
Max Operating Voltage	30V	30V	36V	36V
Topology	Buck-Boost Charger	Buck-Boost Charger	Buck Charger	Boost Charger
IPWM function	No	Yes	Yes	Yes
DPDM function	Yes	No	No	No

6 Typical Application Circuit



7 Terminal Configuration and Functions

TOP VIEW



TERMINAL		I/O	DESCRIPTION
NUMBER	NAME		
1	/CE	I	Chip enable, active low. Pull high (>1.3 V) to disable the device.
2	DIR	I	Operation mode selector. DIR = Low: Charge mode, VBUS charges VBAT battery pack. DIR = High (>1.3 V): Discharge mode, VBAT supplies regulated voltage to VBUS port.
3	PWM	I	Dynamic VBUS output voltage adjustment (Discharge mode only). VBUS formula: $VBUS = VBUS_SET \times (\frac{1}{6} + \frac{5}{6} \times D)$ D = PWM duty cycle (0% ~ 100%). PWM input frequency range: 20 kHz ~ 100 kHz. 100% duty cycle outputs full set voltage; 0% duty cycle outputs 1/6 of set voltage.
4	PG	O	Requires external pull-up resistor to logic supply rail. Charge mode (DIR=Low): PG low = charging in progress; PG high = charge termination completed. Discharge mode (DIR=High): PG high when VBUS output voltage is within 90%~110% of target value; PG low otherwise.
5	IPWM	I	A PWM signal with a frequency ranging from 20 kHz to 100 kHz can be input through the IPWM pin to realize dynamic adjustment of the input or output current, with the adjustment range being 0% to 100% of the set value. This function is valid in both charging and discharging modes, but needs to be used in conjunction with ITUNE.
6	ITUNE	I/O	Use the ITUNE pin to select the current limit target for IPWM adjustment. Connect ITUNE to the negative terminal of the ILIM1 resistor to adjust the current limit value of the VBUS terminal. To dynamically adjust the current limit value of the VBAT terminal, connect ITUNE to the

			negative terminal of the ILIM2 resistor. If this function is not required, leave the ITUNE pin floating.
7	VINREG	I	Charge mode only. Set minimum VBUS operating voltage via external resistor divider. $VBUS_min = VREF \times \left(1 + \frac{RUP}{RDOWN}\right)$ The IC starts charging only when VBUS exceeds $\lfloor (VBUS_min) \rfloor$. If VBUS drops below threshold, input current will be reduced to stabilize voltage; charging stops if regulation fails. Tie VINREG to VCC to disable this function.
8	DT	I	Dead time setting, 4 options: - DT shorted to GND = 20 ns; 68 kΩ resistor to GND = 40 ns; 270 kΩ resistor to GND = 60 ns; - DT open = 80 ns
9	CSEL	I	Battery charge termination voltage setting (Charge mode only): - CSEL shorted to GND: Termination voltage defined by FB2 resistor divider 68 kΩ to GND: 4.2 V (1S lithium battery) 270 kΩ to GND: 8.4 V (2S lithium battery) - CSEL open: 12.6 V (3S lithium battery)
10	FREQ	I	Switching frequency setting, 3 options: - FREQ pin shorted to GND: 200 kHz - FREQ pin connect 68 kΩ resistor to GND: 400 kHz - FREQ pin is open: 600 kHz
11	ILIM1	I	VBUS port current limit programming. Charge mode = input current limit; Discharge mode = output current limit: $IBUS_LIM = \frac{VREF}{RILIM1} \times \frac{RSS1}{RSNS1}$ VREF: Internal reference value 1.21V RSNS1: VBUS current sense resistor (typical 10 mΩ); RSS1: 1 kΩ differential series resistor; Connect a 10 nF capacitor from ILIM1 to GND. Short ILIM1 to GND to disable VBUS current limit function.
12	ILIM2	I	VBAT battery port current limit programming. Charge mode = battery charging current limit; Discharge mode = battery output current limit: $IBAT_LIM = \frac{VREF}{RILIM2} \times \frac{RSS2}{RSNS2}$ VREF: Internal reference value 1.21V RSNS2: VBAT current sense resistor (typical 10 mΩ); RSS2: 1 kΩ differential series resistor; Connect a 10 nF capacitor from ILIM1 to GND. Do NOT short ILIM2 directly to GND.
13	FB1	I	Discharge mode VBUS output voltage feedback divider. 1. Without PWM dynamic adjustment, the Basic formula: $VBUS = VREF \times \left(1 + \frac{RUP}{RDOWN}\right)$ VREF is the internal voltage reference of 1.21 V, and

			RUP and RDOWN are the external voltage divider resistors connected to FB1 respectively 2. With PWM dynamic adjustment: $VBUS = VREF \times \left(1 + \frac{RUP}{RDOWN}\right) \times \left(\frac{1}{6} + \frac{5}{6} \times D\right)$ where D stands for the duty cycle of the PWM signal.
14	AGND	I/O	Analog signal ground
15	COMP	O	Internal control loop compensation pin. Connect RC network to stabilize regulation loop.
16	FB2	I	Charge mode battery termination voltage feedback divider (Only valid when CSEL is shorted to GND). $VBAT = VREF \times \left(1 + \frac{RUP}{RDOWN}\right)$ If CSEL configures fixed 1S/2S/3S voltage, float or ground FB2 pin.
17	SNS2N	I	Negative input of current sense amplifier. Connect an external current sense resistor between SNS2P and SNS2N.
18	SNS2P	I	Positive input of current sense amplifier. Connect an external current sense resistor between SNS2P and SNS2N.
19	VBAT	I	Output node of the converter when DIR = Low, and input node of the converter when DIR = High. Connect to battery cells.
20	BT	PWR	Connect a capacitor between BT pin and SW pin to bootstrap a voltage to provide the bias voltage for high side MOSFET gate driver
21	HD	PWR	High side MOSFET gate driver output
22	SW	PWR	Switching Node
23	LD	PWR	Low side MOSFET gate driver output
24	VCC	O	Output of internal regulator to provide max. 10V voltage for the bias voltage of internal gate drivers. Connect a 1 μF ceramic capacitor from VCC to PGND pin.
25	PGND	PWR	Power Ground.
26	CP_L	I	Input of the charger pump.
27	NC		Leave this pin floating.
28	NC		Leave this pin floating.
29	CP_H	O	Output of the charger pump.
30	VBUS	I	Input node of the converter when DIR = Low, and output node of the converter when DIR = High. Connect to adapter input port or USB port.
31	SNS1N	I	Negative input of current sense amplifier. Connect an external current sense resistor between SNS1P and SNS1N.
32	SNS1P	I	Positive input of current sense amplifier. Connect an external current sense resistor between SNS1P and SNS1N.

	Thermal Pad	-	For thermal dissipation. Connect to AGND and PGND.
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8 Specifications

8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

PARAMETER		MIN	MAX	Unit
Voltage range at terminals ⁽²⁾	VBUS, VBAT, SNS1P, SNS1N, SNS2P, SNS2N, /CE	-0.3	42	V
	SW	-1	42	V
	VCC, PG, DIR, PWM, IPWM, VINREG	-0.3	20	V
	FREQ, ITUNE, ILIM1, ILIM2, COMP, CSEL, DT, FB1, FB2	-0.3	5.5	V
	LD	-0.3	12	V
	BT, HD to SW	-0.3	12	V
T _j	Operating junction temperature range	-40	150	°C
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.

8.2 Handling Ratings

PARAMETER	DEFINITION		MIN	MAX	UNIT
ESD ⁽¹⁾	Human body model (HBM) ESD stress voltage ⁽²⁾	All pins	-2	2	kV
	Charged device model (CDM) ESD stress voltage ⁽³⁾		-750	750	V

- (1) Electrostatic discharge (ESD) to measure device sensitivity and immunity to damage caused by assembly line electrostatic discharges into the device.
- (2) Level listed above is the passing level per ANSI, ESDA, and JEDEC JS-001. JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (3) Level listed above is the passing level per EIA-JEDEC JESD22-C101. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

8.3 Recommended Operating Conditions

PARAMETER		MIN	TYP	MAX	UNIT
V _{BUS}	VBUS voltage range	2.7	5	36	V
V _{BAT}	VBAT voltage range	2		30	V
C _{BUS}	VBUS Bulk Capacitance	30			μF
C _{BAT}	VBAT Bulk Capacitance	30			μF
L	Power Inductor L	2.2		6.8	μH

$R_{SNS1/2}$	Current Sensing Resistor	5	10	20	mΩ
f_{SW}	Switching Frequency	200		600	kHz
f_{PWM}	PWM Signal Frequency Range	20		100	kHz
D_{PWM}	PWM Signal Duty Cycle Range	0		100	%
T_A	Operating ambient temperature	-40		85	°C
T_J	Operating junction temperature	-40		125	°C

8.4 Thermal Information

THERMAL RESISTANCE ⁽¹⁾		QFN-32 (4mm x 4mm)	UNIT
θ_{JA}	Junction to ambient thermal resistance	35	°C/W
θ_{JC}	Junction to case thermal resistance	7	°C/W

(1) Measured on JESD51-7, 4-layer PCB.

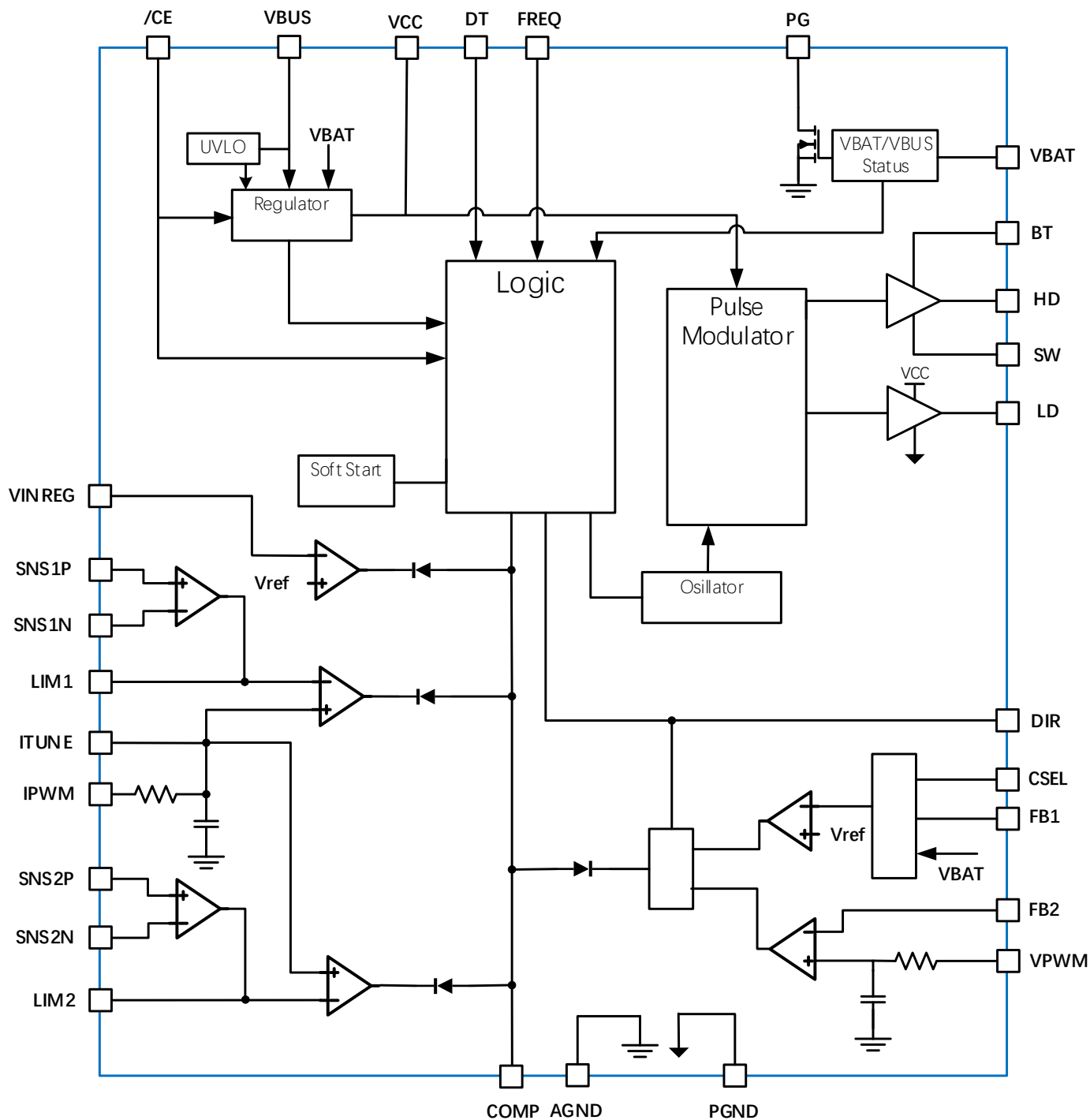
8.5 Electrical Characteristics

$T_J = -40^{\circ}\text{C}$ to 125°C , $V_{\text{BUS}} = 5\text{V}$ and $V_{\text{BAT}} = 3.6\text{V}$, typical values are tested at $T_J = 25^{\circ}\text{C}$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY VOLTAGE (VBUS, VBAT)						
V_{BUS}	Operating voltage	DIR = Low, as input voltage	2.7		36	V
		DIR = High, as output voltage	2		36	V
V_{BAT}	Operating voltage	DIR = Low, as output voltage	1.5		30	V
		DIR = High, as input voltage	2.7		30	V
$V_{\text{UVLO_VBUS}}$	VBUS under-voltage lockout threshold	DIR = Low, rising edge		2.6	2.7	V
		DIR = Low, hysteresis		160		mV
$V_{\text{UVLO_VBAT}}$	VBAT under-voltage lockout threshold	DIR = High, rising edge		2.6	2.7	V
		DIR = High, hysteresis		160		mV
I_{Q}	Standby current into VBUS or VBAT pin (whichever is higher)	/CE = low, controller non-switching		0.7	2	mA
$I_{\text{Q_VBAT}}$	Standby current into VBAT pin under EOC status	/CE = low, VBUS removed			15	μA
I_{SD}	Shutdown current into VBUS or VBAT pin (which is higher)	/CE = high		6	10	μA
	Shutdown current into VBUS or VBAT pin (which is lower)	/CE = high			2	μA
VCC AND DRIVER						
V_{CC}	VCC clamp voltage		9.4	10	10.6	V
$I_{\text{VCC_LIM}}$	VCC current limit	$V_{\text{CC}} = 2\text{V} \sim 10\text{V}$	50	75	100	mA
$R_{\text{HV_pu}}$	High side driver pull up resistor			1.5		Ω
$R_{\text{HV_pd}}$	High side driver pull down resistor			1		Ω
$R_{\text{LV_pu}}$	Low side driver pull up resistor			1.5		Ω
$R_{\text{LV_pd}}$	Low side driver pull down resistor			1		Ω
ERROR AMPLIFIER						
$V_{\text{FB2_REF}}$	FB2 reference voltage		1.214	1.22	1.226	V
$V_{\text{INREG_REF}}$	VINREG reference voltage		1.196	1.226	1.244	V
$V_{\text{ILIMx_REF}}$	ILIMx reference voltage		1.196	1.212	1.228	V
$V_{\text{FB1_REF}}$	FB1 reference voltage		1.196	1.212	1.228	V
G_{mEA}	Error amplifier gm			0.16		mS
R_{OUT}	Error amplifier output resistance ⁽¹⁾			20		M Ω
$I_{\text{BIAS(FBx)}}$	FBx pin input bias current	FBx in regulation			100	nA
OUTPUT TARGET AND THRESHOLD						
$V_{\text{BAT_TRGT}}$	Battery termination target	$R_{\text{CSEL}} = 68\text{ k}\Omega (\pm 10\%)$	4.158	4.2	4.242	V
		$R_{\text{CSEL}} = 270\text{ k}\Omega (\pm 10\%)$	8.316	8.4	8.484	V
		$R_{\text{CSEL}} = \text{open}$	12.474	12.6	12.726	V
$V_{\text{BAT_TERM}}$	Termination threshold over $V_{\text{BAT_TRGT}}$	DIR = Low, rising edge	96.5%	98%	99.5%	
$V_{\text{BAT_RECH}}$	Recharge threshold over $V_{\text{BAT_TRGT}}$	DIR = Low, falling edge		95.8%		
$V_{\text{TRK_CH}}$	Trickle charge threshold over $V_{\text{BAT_TRGT}}$	DIR = Low, rising edge	64%	70%	76%	
		DIR = Low, hysteresis		5%		
$I_{\text{BAT_TRK}}$	Battery trickle charge current, over ILIM2 set current	DIR = Low		10%		

I _{BAT_TERM}	Battery current termination threshold, over ILIM2 set current	DIR = Low, falling edge	4%			
V _{OVP}	OVP threshold, over VBUS target	DIR = high	105%	110%	115%	
CURRENT LIMIT						
I _{LIMx}	ILIM1 current limit accuracy DIR = low	I _{BUS_LIM} R _{SNS1} ≥ 30 mV	-10%10%			
	ILIM2 current limit accuracy DIR = low	I _{BAT_LIM} R _{SNS2} ≥ 30 mV	-5%5%			
	ILIM1 current limit accuracy DIR = high	I _{BUS_LIM} R _{SNS1} ≥ 30 mV	-5%5%			
	ILIM2 current limit accuracy DIR = high	I _{BAT_LIM} R _{SNS2} ≥ 30 mV	-10%10%			
SWITCHING FREQUENCY						
f _{SW}	Switching frequency	R _{FREQ} = 0Ω	180	210	240	kHz
		R _{FREQ} = 68kΩ (±10%)	360	410	460	kHz
		R _{FREQ} = 270kΩ (±10%)	540	600	660	kHz
INDICATION						
t _{PG_deglitch}	PG signal deglitch time	f _{sw} = 200kHz	27	38.5	50	ms
I _{SINK_PG}	PG sink current	V _{PG} = 0.4 V	3.6	4.1	4.6	mA
V _{BUS_PG}	VBUS power good threshold	DIR = High, high limit falling edge (PG from low to high)	110%			
		DIR = High, high limit hysteresis (PG from high to low)	5%			
		DIR = High, low limit rising edge (PG from low to high)	90%			
		DIR = High, low limit hysteresis (PG from high to low)	5%			
LOGIC CONTROL						
R _{PD}	/CE, DIR pin internal pull down resistor		1			MΩ
	PWM pin internal pull down resistor		0.5			MΩ
	IPWM pin internal pull down resistor		1			MΩ
V _{IL}	/CE, DIR, PWM input low voltage		0.4			V
V _{IH}	/CE, DIR PWM, input high voltage		1.2			V
Soft Start						
t _{SS}	Internal soft-start time	From /CE low to 90% VBUS	815			ms
THERMAL SHUTDOWN						
T _{SD}	Thermal shutdown temperature ⁽¹⁾		165			°C
	Thermal shutdown hysteresis ⁽¹⁾		15			°C

9 Functional Block Diagram



10 Feature Description

The SC8804 is bi-directional synchronous boost charge controller for 1- to 6-cell battery with a wide input/output voltage range. The charging and discharging mode is selected by DIR pin.

The SC8804 operates as a charger when DIR pin is pulled logic low, and it is called charging mode. In this mode, SC8804 works in boost switching mode to step up voltage and charges battery. The SC8804 features trickle charging, CC charging, CV charging and charging termination functions. The SC8804 supports self-adaptive feature for different adaptors and can limit the charging current automatically to avoid overloading adaptors.

The SC8804 operates in reverse condition mode when DIR pin is pulled logic high, and it is called discharging mode. In this mode, the SC8804 steps down voltage to output.

10.1 Charging Mode

The charge and discharge modes of SC8804 are controlled by the DIR signal.

When the DIR input level is low, SC8804 operates in charge mode. In this state, power flows from the adapter interface (VBUS pin) to charge the battery (VBAT pin), and the power path is shown in the figure below.

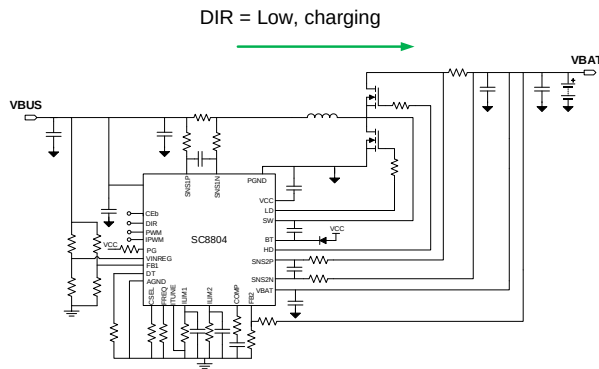


Figure 1. Charging mode when DIR=LOW

10.1.1 Charge Termination Voltage Setting (CSEL and FB1)

In charging mode, termination voltage is set by one of two cases.

Case 1: Set the termination voltage using CSEL pin. When the SC8804 is enabled, the IC checks the resistor value at CSEL pin and set the charge termination voltage internally.

Table 1 shows the resistor value for different charge termination voltage.

Table 1. CSEL resistor value vs Charge termination voltage

CSEL resistor value	Charge termination voltage
68kΩ	4.2V (1S battery)
270kΩ	8.4V (2S battery)
Open	12.6V (3S battery)
0Ω	Set by FB2 pin resistors

When setting the charge termination voltage by CSEL pin, the battery voltage is monitored by VBAT pin voltage directly. In this case, FB2 pin should be open or connected to GND.

The SC8804 checks the resistor value at CSEL pin only during the startup process. After SC8804 is enabled, termination voltage change by changing resistor value at CSEL pin will not be valid until system restarts (Off and on the VBUS voltage or cycling the /CE voltage)

Case 2: Set the termination voltage using resistor divider at FB2 pin. When CSEL pin is connected to GND, termination voltage is adjusted by external resistor divider at FB2 pin and is calculated as:

$$VBAT = V_{FB2_REF} \times \left(1 + \frac{R_{UP}}{R_{DOWN}}\right)$$

With V_{FB2_REF} voltage is 1.22V and R_{UP} and R_{DOWN} resistors are the resistor divider between VBAT to FB2 pins.

10.1.2 CC Charge current setting (ILIMx)

The SC8804 can adjust the current limit of both adaptor side (VBUS) and battery side (VBAT) by resistors at ILIM1 and ILIM2 pins.

Table 2 Charge current limit setting

Control Pins	Description
ILM1	Monitor R_{SNS1} to set the adaptor side (VBUS) charge current (IBUS_LIM)
ILM2	Monitor R_{SNS2} to set the battery side (VBAT) charge current (IBAT_LIM)

The SC8804 senses the VBUS and VBAT current by monitoring R_{SNS1} and R_{SNS2} respectively as below figure shows.

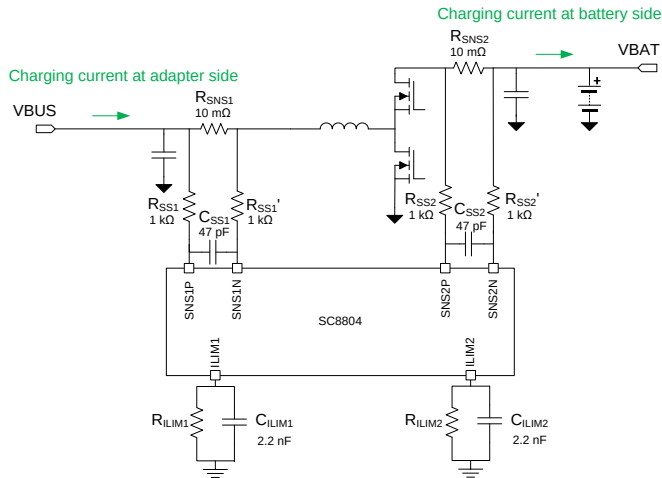


Figure 2 Charge current monitoring circuit

R_{SNSx} is the current sense resistor (x means 1 or 2) connected in series with the input supply or output of the charger. The SC8804 monitors the voltage across the sense resistors R_{SNSx} through R_{SSx} and $R_{SSx'}$ and calculate the input and output current. C_{SSx} is the filter capacitor.

The $ILIMx$ pin is used to set the charge current limit. Connect the R_{ILIMx} resistor between $ILIMx$ pin and GND with 10nF capacitor in parallel.

The current limit is calculated as:

$$I_{BUS_LIM} = \frac{V_{LIM_REF}}{R_{ILIM1}} \times \frac{R_{SS1}}{R_{SNS1}}$$

$$I_{BAT_LIM} = \frac{V_{LIM_REF}}{R_{ILIM2}} \times \frac{R_{SS2}}{R_{SNS2}}$$

Where:

V_{LIM_REF} = Internal reference voltage 1.21V;

R_{ILIMx} = Resistors at $ILIMx$ pin;

R_{SNSx} = Current sense resistors;

R_{SSx} = Resistors between current sense resistor and the SC8804 pins (SNSxP, SNSxN).

To get accurate values, keep below two conditions;

- 1) R_{SNSx} should be placed between MOSFET and input/output capacitor.
- 2) R_{SS1} and $R_{SS1'}$ should be same value; R_{SS2} and $R_{SS2'}$ should be also same value. Typically 1kΩ resistor is used.

If R_{SNSx} is changed, $R_{SSx}/R_{SSx'}$ values need to be adjusted accordingly with below calculation:

$$\frac{R_{SNSx}}{R_{SSx}} = \frac{10 \text{ m}\Omega}{1 \text{ k}\Omega}$$

For example, If R_{SNSx} is 20mΩ, then $R_{SSx}/R_{SSx'}$ should be 2kΩ; if R_{SNSx} is 5mΩ, then $R_{SSx}/R_{SSx'}$ should be 500Ω.

In charging mode, if both VBUS and VBAT current limits are programmed, the SC8804 controls the charge current as soon as one of VBUS and VBAT current reaches its current limit.

For example, if the adaptor side (VBUS) current reaches its current limit set value (ex. 3A) first, then adaptor side current is regulated to 3A; whereas if battery side (VBAT) current limit reaches its current limit set value (ex. 6A) first, then battery side current is regulated to 6A, and at this case, adaptor side current could be lower than VBUS current limit set value.

If VBUS current limit is not required, connect $ILIM1$ pin to GND. Then VBUS current is not regulated and the SC8804 regulates VBAT current limit for constant current charge.

In charging mode, VBAT current limit is necessary, otherwise, the SC8804 will misjudge the end of charge condition.

It is not allowed to set any of the current limits to 0A. Keep the minimum current limit above 0.3A.

10.1.3 Dynamic Power management (VINREG)

The SC8804 features dynamic power management. The valid minimum VBUS threshold is programmed by VINREG pin. When VBUS reaches minimum VBUS threshold, the charge current is reduced automatically. With this feature, even in case the adaptor output current capability is lower than the SC8804 charge current set value, the SC8804 can automatically reduce the charge current to adaptor output current to avoid the adaptor overload and abnormal charging, and keep VBUS voltage to minimum operating voltage.

The minimum operating VBUS voltage is calculated as:

$$V_{BUS_min} = V_{INREG_REF} \times \left(1 + \frac{R_{UP}}{R_{DOWN}}\right)$$

Where;

$V_{INREG_REF} = 1.226V$;

R_{UP} and R_{DOWN} = The divider resistor connected to VINREG pin.

The SC8804 operates normally when VBUS voltage is higher than programmed threshold voltage (V_{BUS_min}). This function is valid only in charge mode. If this function is not required, connect VINREG pin to VCC.

10.2 Charging curve

When DIR pin is “L”, the SC8804 enters into charge mode with charge management such as trickle charging, CC charging, CV charging and charging termination (end of charging).

Typical charge curve is shown in Figure 3.

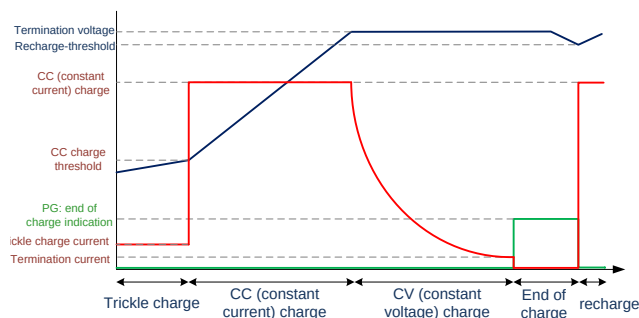


Figure 3. SC8804 Charge curve

10.2.1 Trickle Charging

The SC8804 operates in trickle charging mode if the VBAT voltage is lower than CC (constant current) charge threshold voltage. The CC charge threshold voltage is typically 70% of charge termination voltage.

In trickle charge mode, the SC8804 reduces the VBAT charge current to 10% of programmed current limit (IBAT_LIM). For example, if VBAT current limit (IBAT_LIM) is programmed to 6A, in trickle charge mode, charge current is reduced to 0.6A automatically. When VBAT voltage exceeds CC charge threshold voltage, the SC8804 recovers the charge current to VBAT current limit value and operates as CC charge mode.

10.2.2 Constant Current Charge mode

The SC8804 operates in CC quick charge mode if the VBAT voltage is higher than quick charge threshold voltage. During CC quick charge mode, the output current is controlled by ILIMx pin. For the detail information, please refer to [10.1.2 CC charge current setting \(ILIMx\)](#)

10.2.3 Constant Voltage Charging

The SC8804 operates in CV charging mode if VBAT voltage reaches to 98% of VBAT termination voltage. In CV charging

mode, the SC8804 maintains battery voltage and reduce the charge current automatically until the battery is charged fully.

10.2.4 Charge termination / End of charge indication (PG)

In charging mode, once below two conditions are all valid, the SC8804 recognizes that the battery is fully charged and it will terminate charging automatically:

- 1) The battery voltage is higher than 98% of battery termination threshold.
- 2) With monitoring the R_{SNS2} , VBAT current becomes lower than 1/25 of ILIM2 programmed current.

After stopping charging, the SC8804 turns off VCC voltage and operates in a low power standby mode and reduces the current consumption from battery side.

The SC8804 indicates the end of charge status with PG pin. PG is open drain output and it requires an external pullup resistor.

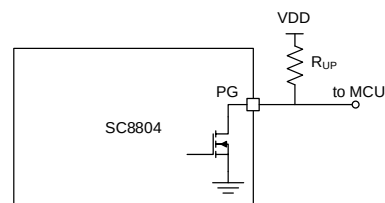


Figure 4 PG pin structure

In charging mode, PG output is pulled LOW but after end of charge, PG output is pulled HIGH by external pullup resistor and indicates that the battery is fully charged.

If MCU does not need to check PG, remain PG pin open.

10.2.5 Recharging

After charging termination, once the SC8804 detects the battery voltage falls below 95% of programmed termination voltage, the SC8804 automatically restarts charging in CC phase. In this period, VCC voltage is turned on, PG voltage is pulled “L” to indicate that the SC8804 is in charging mode.

10.3 Reverse Direction Discharge mode

When DIR pin is “H”, the SC8804 enters reverse direction discharging mode.

In discharging mode, the battery (VBAT) is discharged to adaptor/USB (VBUS), which becomes output. Figure 5 shows the power path at discharging mode.

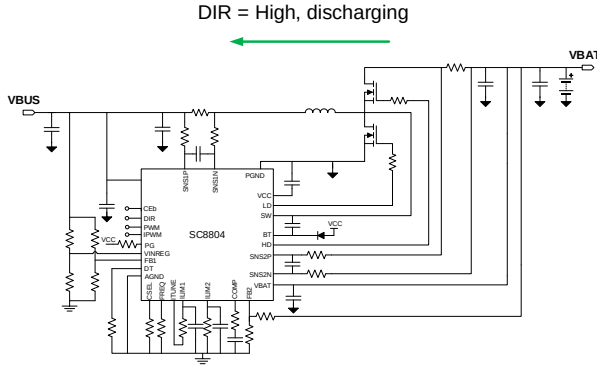


Figure 5 SC8804 Reverse direction discharge mode.

10.3.1 VBUS discharge voltage setting (FB1)

In discharging mode, VBUS discharge voltage is set by external resistor divider as FB1 pin and is calculated as:

$$VBUS = V_{FB1_REF} \times \left(1 + \frac{R_{UP}}{R_{DOWN}}\right)$$

Where:

V_{FB1_REF} = Internal reference voltage 1.21V

R_{UP} and R_{DOWN} = Resistor divider at FB1 connected to VBUS.

The SC8804 can operate with quick charge or PD controller ICs and these ICs can change the FB1 pin voltage for real-time discharge output voltage control.

10.3.2 VBUS Discharge voltage real-time control (PWM)

In discharging mode, the SC8804 supports VBUS output voltage change in two ways: one is to change FB1 pin divider ratio, the other is to control VBUS voltage by PWM signal input.

For the 2nd way, the FB1 resistor divider value is fixed, VBUS output voltage is controlled by duty cycle (D) of PWM signal, which is supplied to PWM pin and in the range of 10kHz to 100kHz. VBUS output voltage is calculated as:

$$VBUS = V_{BUS_SET} \times \left(\frac{1}{6} + \frac{5}{6} \times D\right)$$

Where;

V_{BUS_SET} = VBUS output voltage which is set by FB1 resistor divider;

D = Duty cycle of PWM signal.

The relationship between VBUS output voltage and D is showed in Figure 6.

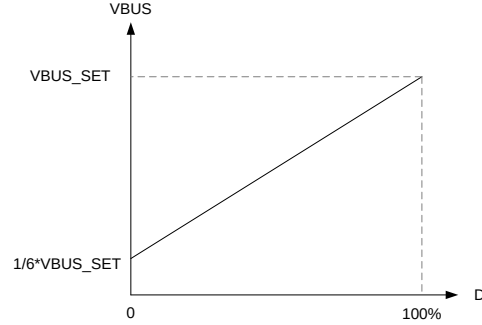


Figure 6 VBUS output voltage vs PWM duty cycle.

If PWM input signal keeps “H”, means 100% of duty cycle, then the output voltage become the programmed voltage by FB1 resistor divider.

If PWM input signal keeps “L”, means 0% of duty cycle, then the output voltage become the 1/6 of programmed voltage by FB1 resistor divider. Make sure the controlled output voltage is still lower than battery voltage so the SC8804 can work in buck operation mode.

Real-time PWM output control is valid only in discharging mode.

10.3.3 Discharge current setting (ILIMx)

In discharging mode, the VBUS and VBAT current is sensed by R_{SNS1} and R_{SNS2} current sense resistors.

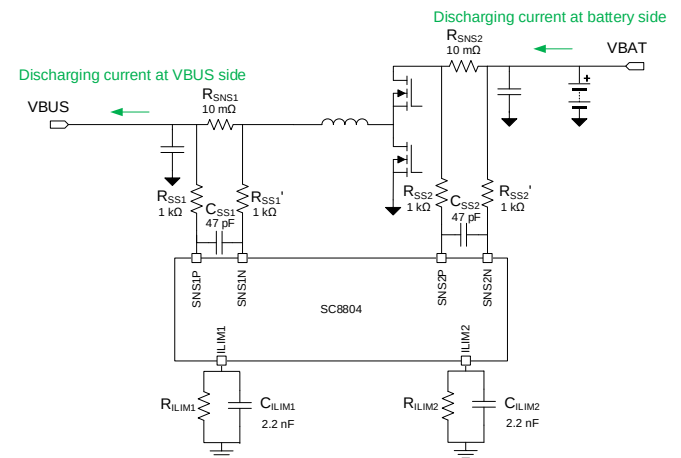


Figure 7 Discharge current monitoring circuit.

The SC8804 features current limit function. VBUS and battery side current limits are set by ILIM1 and ILIM2 pins and current limits are calculated as:

$$I_{BUS_LIM} = \frac{V_{LIM_REF}}{R_{ILIM1}} \times \frac{R_{SS1}}{R_{SNS1}}$$

$$I_{BAT_LIM} = \frac{V_{LIM_REF}}{R_{ILIM2}} \times \frac{R_{SS2}}{R_{SNS2}}$$

Please refer to for proper R_{SNSx} and R_{SSx} values.

The current limit, set by ILIMx, in discharging mode is equally applied to charging mode: in charging mode, the current limit is charging current and in discharging mode, the current limit is maximum discharging current.

If the current limits required by charging mode and discharging mode are different, please refer to the circuit in Figure 16 to change the limits accordingly.

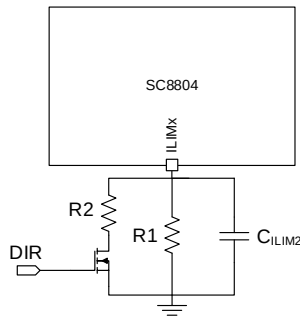


Figure 8 Current limit control using DIR signal

It is not allowed to set any of the current limits to 0A. Keep the minimum current limit above 0.3A.

10.3.4 Discharge voltage POWER GOOD indicator (PG)

In discharging mode, PG signal indicates discharge voltage status.

If VBUS output voltage remains in between 90% ~ 110% of programmed voltage, PG pin become high impedance and due to the output pullup resistor, PG out becomes “H” to indicate the output voltage is normal.

If VBUS voltage is out of normal voltage range, PG out becomes “L”.

If this indication is not required, remain PG pin open.

10.4 Other signals

10.4.1 Chip Enable (/CE)

The SC8804 turns on/off by /CE signal. When /CE input is “L”, the SC8804 turns on; when /CE input is “H”, the SC8804 turns off.

10.4.2 Charging/Discharging mode control (DIR)

The charging mode and discharging mode is decided by DIR signal. When DIR input is “L”, the SC8804 operates in charging mode; when DIR input is “H”, the SC8804 operates in discharging mode.

10.4.3 Switching frequency setting (FREQ)

The one of three switching frequency is selectable by resistor value at FREQ pin:

FREQ resistor	Switching frequency f_{sw}
0Ω	200kHz
68kΩ (±10%)	400kHz
Open	600kHz

The accuracy of the resistor at FREQ is allowed ±10%. The real-time switching frequency change is not valid and new resistor value change will be applied in next turn on.

10.4.4 Dead time setting (DT)

The one of four dead time is selectable by resistor value at DT pin:

DT resistor	Dead time
0Ω	20ns
68kΩ (±10%)	40ns
270kΩ (±10%)	60ns
Open	80ns

The accuracy of the resistor at DT is allowed ±10%. DT does not support the real-time change and new resistor value change will be applied in next turn on.

When driving large power MOSFET with high C_{iss} value, or adding driver resistors at LDx or HDx to adjust the MOSFET turning on/off time, it is suggested to check and change the dead time to prevent MOSFET shoot-through.

10.4.5 VCC driver voltage

The SC8804 generates driver voltage VCC internally. The VCC is selected higher voltage between VBUS and VBAT, and clamped to 10V if it is higher than 10V.

The driving signal LD to drive low side MOSFET (Q2) is directly supplied from VCC; the driving signal HD to drive high side MOSFET (Q1) is supplied from the diode in between VCC to BTx pin, which is generated by bootstrap circuit with bootstrap capacitor between BT and SW.

10.4.6 Feedback compensation (COMP)

The feedback loop can be compensated by adjusting the external components to the COMP pin.

11 Application Information

11.1 Input and output capacitor selection

The switching frequency of the SC8804 is in the range of 200kHz ~ 600kHz. Since MLCC ceramic capacitor has good high frequency filtering with low ESR, above 60μF X5R or X7R capacitors with higher voltage rating than operating voltage with margin is recommended. For example, if the highest operating Vin/Vout voltage is 12V, select at least 16V capacitor and to secure enough margin, 25V voltage rating capacitor is recommended.

The high capacitance electrolytic capacitor and tantalum capacitor can be used for stable input and output but capacitor voltage rating should be higher than the highest operating voltage. When the tantalum capacitor is used, at least 1μF ceramic capacitor is placed in parallel. If the electrolytic capacitor is used, much more ceramic capacitors are required. For example, if a 47μF electrolytic capacitor is used, the ceramic capacitors' capacitance is allowed to reduce to 30μF ~ 40μF. Even higher capacitance electrolytic capacitor is used, at least 20μF ceramic capacitor is required.

11.2 Inductor selection

For the SC8804 system stability, the inductance of 2.2μH ~ 10μH inductor is required. High inductance (4.7μH ~ 10μH) is used in the system where the input voltage and output voltage difference is big, such as 3.6V Vin and 15V Vout; Low inductance (2.2μH) is used in the system which the input voltage and output voltage difference is small but high current is required. Typically, 3.3μH inductor is recommended. The inductance can be adjusted for high efficiency and optimization in application.

The inductor DC resistance value (DCR) affects the conduction loss of switching regulator, so around 10mΩ DCR is recommended for the first selection. If the power is relatively small, high DCR inductor can be selected. But if switch on current is high, just like around 10A, then select the lowest DCR inductor as much as possible because 10mΩ DCR also causes 1W power loss.

The inductor saturation current I_{SAT} should be higher than input output current with sufficient margin.

11.3 Current sense resistor

The RSNS1 and RSNS2 are current sense resistors and 5mΩ ~ 20mΩ resistor value is recommended.

Using higher resistor value in high current application causes higher conduction loss. Typically, 10mΩ is recommended. Resistor value can be adjusted depending on current limit and target power efficiency. If R_{SNSx} valued is adjusted, related R_{SSx} value should be adjusted simultaneously.

Please refer to [10.1.2 CC Charge current setting \(ILIMx\)](#) for proper R_{SNSx} and R_{SSx} values.

The resistor power rating and temperature coefficient should also be considered.

The power dissipation is roughly calculated as $P=I^2R$, and I is the highest current flowing through the resistor. The resistor power rating should be higher than roughly calculated power dissipation.

The resistor value can be varied if the temperature increased and the variation is decided by temperature coefficient along with temperature change. If high accuracy of current limit is required, select lower temperature coefficient resistor as much as possible.

11.4 MOSFET selection

The SC8804 is a synchronous 2-switch boost charger controller and it requires 2 NMOS for power switching circuit.

The V_{DS} of MOSFET should be higher than the highest operating voltage with enough margin (recommend more than 10V higher). For example, if the highest operating voltage is 20V, at least 30V rated V_{DS} MOSFET should be selected; If the highest operating voltage is 24V, 40V V_{DS} voltage rating should be selected.

In the application, if the input and output voltage are higher than 10V, driver circuit voltage can reach 10V, and V_{GS} voltage rating of MOSFET should be selected higher than ±10V.

Considering PCB parasitic parameters during operation, driver voltage can be higher than VCC due to transient overshoot, and ±20V V_{GS} is recommended to secure sufficient margin.

The MOSFET current I_D should be higher than the highest input and output current with enough margin.

To ensure the sufficient current capability in relatively high temperature circumstance, the current rate at $T_A=70^{\circ}C$ or T_C

= 100°C should be considered. In addition, the power dissipation value P_D should also be considered and higher P_D is better in applications. Make sure that MOSFET power consumption must not exceed P_D value.

The MOSFET $R_{DS(ON)}$ and input capacitor C_{ISS} impact power efficiency directly. Typically, lower $R_{DS(ON)}$ MOSFET has higher C_{ISS} . The $R_{DS(ON)}$ is related to conduction loss. Higher $R_{DS(ON)}$ results in higher conduction loss, thus lower efficiency and higher thermal dissipation; the C_{ISS} is related to MOSFET switch on/off time, and longer on/off time results in higher switching loss and lower efficiency. The proper MOSFET should be selected based on tradeoff between the $R_{DS(ON)}$ and C_{ISS} .

If high C_{ISS} MOSFET is selected, the switching on and off time become longer, then the dead time should be adjusted with DT pin to avoid simultaneous turn on for both high side and low side MOSFETs.

11.5 Driver resistor and SWx snubber circuit

For a convenient adjustment of MOSFET switching time and transient overshoot at EMI debugging, recommend to add 0603 series resistor between driver pins (LD, HD) and MOSFET Gate pins, and add RC snubber (0603) circuit at SW (refer to Figure 9 Driver resistor and SW snubber circuit)

The driver resistor should be placed near to MOSFET Gate pin. At first, add 0Ω and adjust the resistor value appropriately within 10Ω. After increasing the driver resistor value, the on time of high side and low side MOSFET should be monitored. If the dead time is insufficient, adjust dead time accordingly.

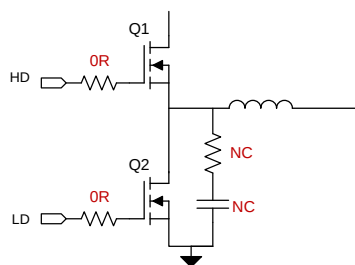


Figure 9 Driver resistor and SWx snubber circuit

The RC snubber circuit is required when the overshoot at SWx needs to be suppressed. Leave RC snubber circuit as NC at the first time.

12 Layout Guide

This chapter defines the mandatory PCB layout rules for SC8804, covering power loop routing, current sampling circuit, MOS drive signal, analog/power ground separation, EMI optimization and sensitive signal wiring. All layout designs shall follow the core principles: minimized power loop area, strict separation of AGND and PGND, short & straight high-frequency routing, sensitive signal isolation and minimal parasitic parameters.

A single-point connection between AGND and PGND is mandatory to eliminate ground loop interference and ensure the stability of sampling and control circuits.

12.1 Grounding Layout Rules

Analog Ground (AGND) and Power Ground (PGND) must be strictly partitioned without overlapping or multi-point bridging.

- a) Single-Point Ground Connection: AGND pin and PGND pin shall be connected at a single point. It is recommended to implement the single-point connection at the IC thermal pad to isolate power noise from analog small-signal circuits.
- b) AGND Wiring Rule: All analog small-signal components for FBx, VINREG, ILIMx, COMP, DT, FREQ and CSEL must be grounded directly to the IC AGND pin with the shortest path, avoiding PGND power routes to prevent noise coupling.

12.2 Power Loop & Bulk Capacitor Layout Rules

Power loop optimization is the key to reducing switching noise and improving EMI performance. All power loops shall be minimized in area with short and wide routing.

- a) Power Loop: The PGND trace of the VBAT bulk capacitor shall be connected to the PGND of boost low side MOSFET with the shortest and widest possible path. The loop formed by VBAT bulk capacitor → current sense resistor → upper/lower switching MOSFETs must be minimized.
- b) 100nF Capacitor Near Current Sense Resistor: The 100nF MLCC capacitor placed between the current sense resistor and MOSFET shall be placed close to the switching MOSFET. Its PGND terminal shall be routed to the corresponding lower MOSFET PGND with the shortest path.
- c) VCC/VBUS/VBAT Filter Capacitor: The 1μF MLCC capacitors for VCC, VBUS and VBAT pins shall be placed close to the IC pins. The grounding terminals of these capacitors shall connect to the IC PGND pin via the shortest path.

12.3 Current Sampling Circuit Layout Rules

The current sampling circuit is a high-precision sensitive circuit, which must be isolated from high-frequency switching signals to ensure sampling accuracy.

- a) The differential routing from the current sense resistor to SNSXP/SNSXN pins shall be tapped from the center pads of the sense resistor. The differential traces shall be routed strictly back to the IC SNS pins and keep away from SWx, LDx and HDx high-noise traces.
- b) The differential resistors and capacitors matched with the current sampling circuit shall be placed close to the IC to shorten the sampling signal path and reduce parasitic interference.

12.4 MOS Gate Drive & Switch Signal Layout Rules

- a) Trace Width Requirement: the routing width of LD, Hx and SW signals shall be $\geq 15\text{mil}$ to meet current carrying capacity and reduce trace impedance.
- b) Drive Resistor Placement: the gate drive series resistors for LD and HD MOSFETs shall be placed as close to the MOSFET pins as possible to suppress gate oscillation and optimize EMI performance.
- c) Loop optimization & routing isolation

- LD loop optimization: The loop composed of LD → lower MOSFET gate → lower MOSFET source PGND → IC PGND shall be minimized. LD traces shall be routed side by side with PGND traces to reduce loop area.
 - HD loop optimization: The loop composed of HD → upper MOSFET gate → upper MOSFET source PGND → IC SW shall be minimized. HD traces shall be routed side by side with the corresponding SW traces.
 - Strict routing isolation: Do not route LD traces parallel with HD traces; do not route LD traces parallel with SWx traces, to avoid crosstalk between high-frequency drive signals.
- d) BT & HD Matching Capacitor: the 100nF capacitor between HD and BT shall be placed close to the IC pins to ensure stable gate drive voltage and suppress high-frequency noise.

12.5 Analog Sensitive Signal Layout Rules

All analog feedback, compensation and configuration signals are susceptible to switching noise interference, requiring independent grounding and signal isolation.

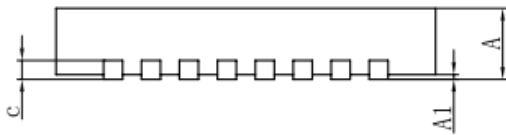
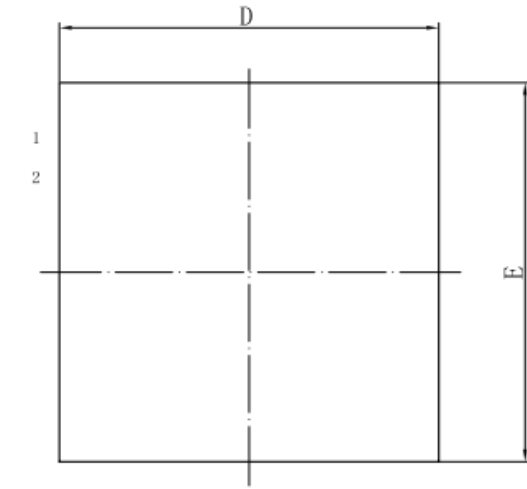
- a) FBx and VINREG: The voltage divider resistors for FBx and VINREG pins shall be placed close to the IC. All grounding terminals shall avoid PGND power paths and be directly connected to the IC AGND pin. FBx and VINREG signal traces must keep away from SWx, LDx and HDx high-frequency switching traces.
- b) ILIMx & COMP: The peripheral components of ILIMx and COMP pins shall be grounded directly to AGND while avoiding PGND power routes. Their signal traces shall be isolated from SWx/LDx/HDx traces.
- c) DT, FREQ, CSEL: The configuration components for DT, FREQ and CSEL pins shall be placed close to the IC. All grounding paths shall avoid PGND and be directly connected to AGND to ensure accurate parameter configuration.

12.6 External Control Signal Grounding Rules

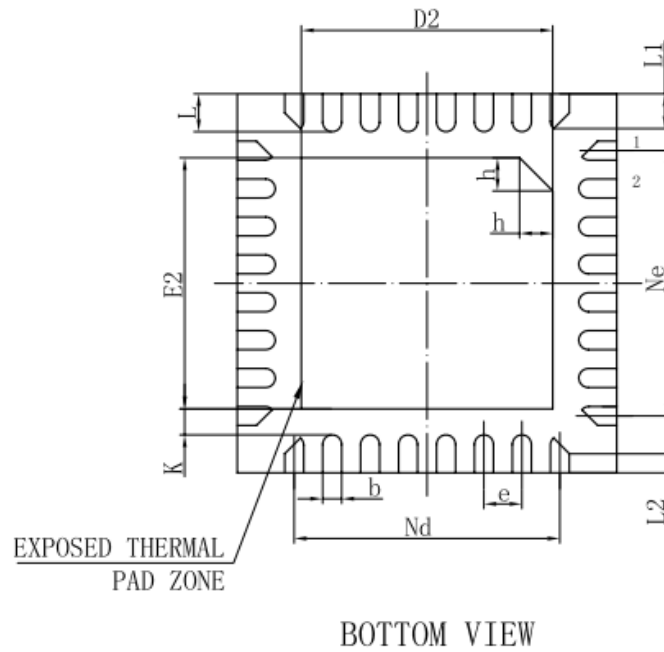
When MCU outputs control signals (including CE, DIR, PWM, IPWM) to control the power management IC, the MCU grounding path shall avoid the PGND power loop. The MCU ground shall be connected to the AGND of the power management IC to prevent power noise from interfering with digital control signals

MECHANICAL DATA

QFN32L(0404x0.75-0.40)

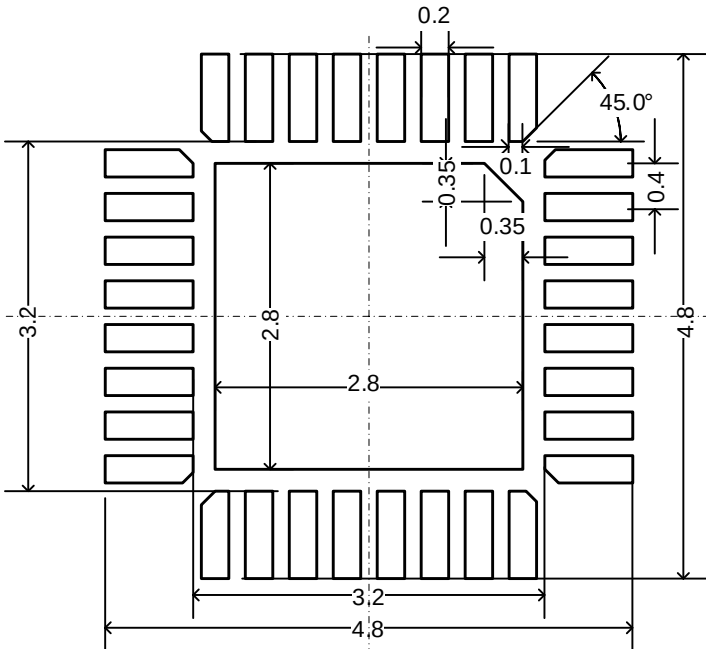


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0	0.02	0.05
b	0.15	0.20	0.25
c	0.18	0.20	0.25
D	3.90	4.00	4.10
D2	2.60	2.65	2.70
e	0.40BSC		
Nd	2.80BSC		
E	3.90	4.00	4.10
E2	2.60	2.65	2.70
Ne	2.80BSC		
K	0.20	-	-
L	0.35	0.40	0.45
L1	0.30	0.35	0.40
L2	0.15	0.20	0.25
h	0.30	0.35	0.40
L/P载体尺寸 (mm)	112*112		



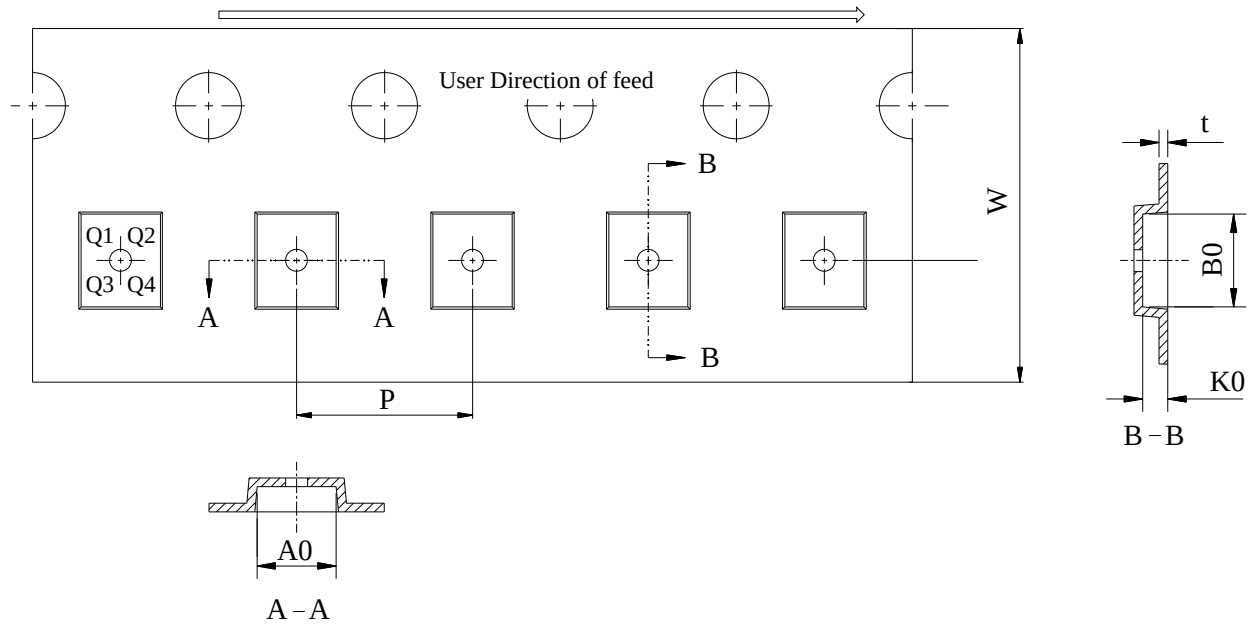
RECOMMENDED FOOTPRINT

QFN32L (0404x0.75-0.4)



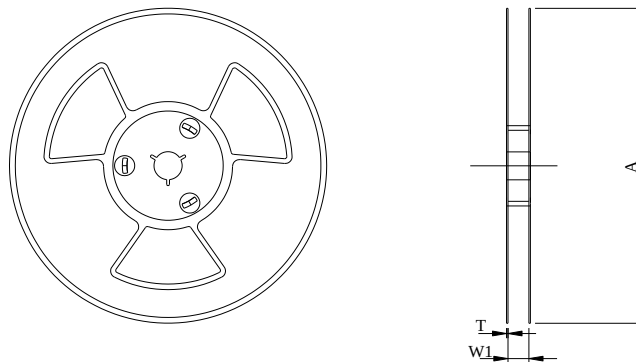
TAPE AND REEL INFORMATION

Carrier Tape



Item	W	P	A0	B0	K0	t	Pin1 Quadrant
Size (mm)	12.00 ± 0.30	8.0 ± 0.10	4.30 ± 0.10	4.30 ± 0.10	1.10 ± 0.10	0.30 ± 0.05	Q1

REEL



Item	A	W1	T
Size (mm)	330 ± 2	12.4 ± 2	2.1 ± 0.15

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